

APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C ⁽¹⁾		STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C ⁽²⁾
	VOLTAGE	100 V AC		STORAGE HUMIDITY RANGE	40 % TO 70 % ⁽²⁾
	CURRENT	0.5 A (SIGNAL CONTACT) ⁽³⁾  3 A (MF CONTACT) 		OPERATING HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	QT AT
CONSTRUCTION					
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	x x
MARKING		CONFIRMED VISUALLY.			x x
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE		100 mA(DC OR 1000Hz)		SIGNAL CONTACT : 90 mΩ MAX. MF CONTACT : 30 mΩ MAX. 	x -
INSULATION RESISTANCE		250 V DC.		1000 MΩ MIN.	x -
VOLTAGE PROOF		300 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	x -
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES		MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 40 N MAX. WITHDRAWAL FORCE: 4 N MIN.	x -
MECHANICAL OPERATION		500 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX.  ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x -
VIBRATION		FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x -
SHOCK		490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			x -
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)		EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX. 	x -
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER: WITHIN 2~3 MIN)		② INSULATION RESISTANCE : 1000 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x -
SULFUR DIOXIDE		EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		NO HEAVY CORROSION.	x -
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	x -
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.	x -
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
	6	DIS-F-004173	TH. SANO	KI. HIROKAWA	09. 09. 15
REMARKS ⁽¹⁾ INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING. ⁽²⁾ "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB. ⁽³⁾ THE RATED CURRENT APPLIES TO PER CONTACT.  Unless otherwise specified, refer to JIS-C-5402.			APPROVED	HS. OKAWA	09. 04. 28
			CHECKED	HS. OZAWA	09. 04. 28
			DESIGNED	KI. HIROKAWA	09. 04. 28
			DRAWN	KI. HIROKAWA	09. 04. 28
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC4-159082-00
	SPECIFICATION SHEET		PART NO.	FX18-60S-0. 8SH	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL579-0010-3-00	 1/1

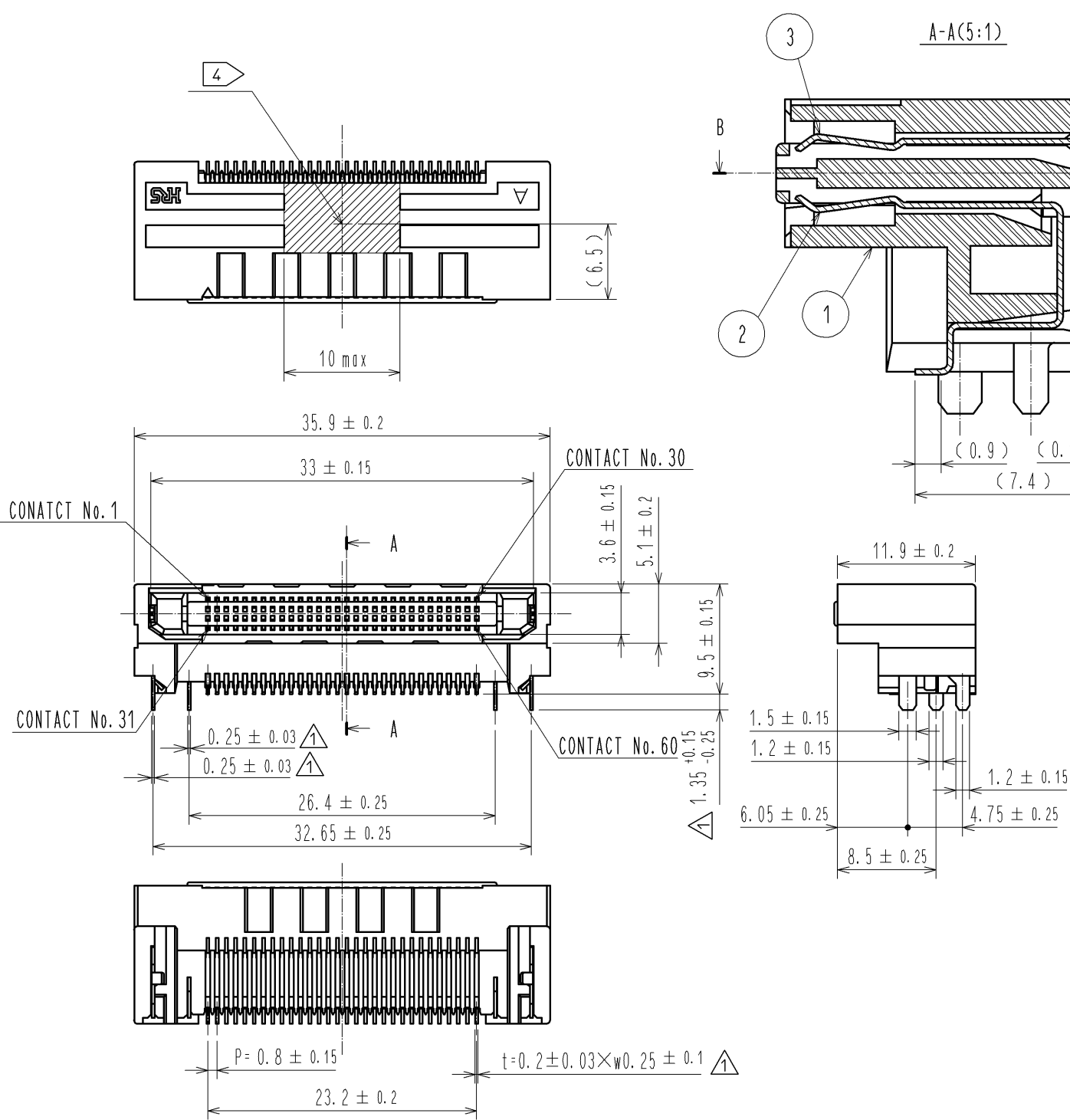
APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C ⁽¹⁾		STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C ⁽²⁾
	VOLTAGE	100 V AC		STORAGE HUMIDITY RANGE	40 % TO 70 % ⁽²⁾
	CURRENT	0.5 A (SIGNAL CONTACT) ⁽³⁾  3 A (MF CONTACT) 		OPERATING HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	QT AT
CONSTRUCTION					
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	x x
MARKING		CONFIRMED VISUALLY.			x x
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE		100 mA(DC OR 1000Hz)		SIGNAL CONTACT : 90 mΩ MAX. MF CONTACT : 30 mΩ MAX. 	x -
INSULATION RESISTANCE		250 V DC.		1000 MΩ MIN.	x -
VOLTAGE PROOF		300 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	x -
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES		MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 40 N MAX. WITHDRAWAL FORCE: 4 N MIN.	x -
MECHANICAL OPERATION		500 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX.  ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x -
VIBRATION		FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x -
SHOCK		490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			x -
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)		EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX. 	x -
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER: WITHIN 2~3 MIN)		② INSULATION RESISTANCE : 1000 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x -
SULFUR DIOXIDE		EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		NO HEAVY CORROSION.	x -
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	x -
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.	x -
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
	6	DIS-F-004173	TH. SANO	KI. HIROKAWA	09. 09. 15
REMARKS ⁽¹⁾ INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING. ⁽²⁾ "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB. ⁽³⁾ THE RATED CURRENT APPLIES TO PER CONTACT.  Unless otherwise specified, refer to JIS-C-5402.			APPROVED	HS. OKAWA	09. 04. 28
			CHECKED	HS. OZAWA	09. 04. 28
			DESIGNED	KI. HIROKAWA	09. 04. 28
			DRAWN	KI. HIROKAWA	09. 04. 28
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC4-159561-00
	SPECIFICATION SHEET		PART NO.	FX18-60P-0. 8SV	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL579-0017-2-00	 1/1

APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C ⁽¹⁾		STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C ⁽²⁾
	VOLTAGE	100 V AC		STORAGE HUMIDITY RANGE	40 % TO 70 % ⁽²⁾
	CURRENT	0.5 A (SIGNAL CONTACT) ⁽³⁾ 3 A (MF CONTACT)		OPERATING HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	QT AT
CONSTRUCTION					
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	x x
MARKING		CONFIRMED VISUALLY.			x x
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE		100 mA(DC OR 1000Hz)		SIGNAL CONTACT : 90 mΩ MAX. MF CONTACT : 30 mΩ MAX.	x —
INSULATION RESISTANCE		250 V DC.		1000 MΩ MIN.	x —
VOLTAGE PROOF		300 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	x —
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES		MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 30 N MAX. WITHDRAWAL FORCE: 3 N MIN.	x —
MECHANICAL OPERATION		500 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
VIBRATION		FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
SHOCK		490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			x —
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)		EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX.	x —
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER: WITHIN 2~3 MIN)		② INSULATION RESISTANCE : 1000 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
SULFUR DIOXIDE		EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		NO HEAVY CORROSION.	x —
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	x —
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	x —
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
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REMARKS ⁽¹⁾ INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING. ⁽²⁾ "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB. ⁽³⁾ THE RATED CURRENT APPLIES TO PER CONTACT. Unless otherwise specified, refer to JIS-C-5402.			APPROVED	HS. OKAWA	09. 10. 13
			CHECKED	K.I. HIROKAWA	09. 10. 13
			DESIGNED	TH. SANO	09. 10. 13
			DRAWN	K.I. HIROKAWA	09. 09. 14
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC4-159074-00
HRS	SPECIFICATION SHEET		PART NO.	FX18-40P-0. 8SH	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL579-0002-5-00	△ 1/1

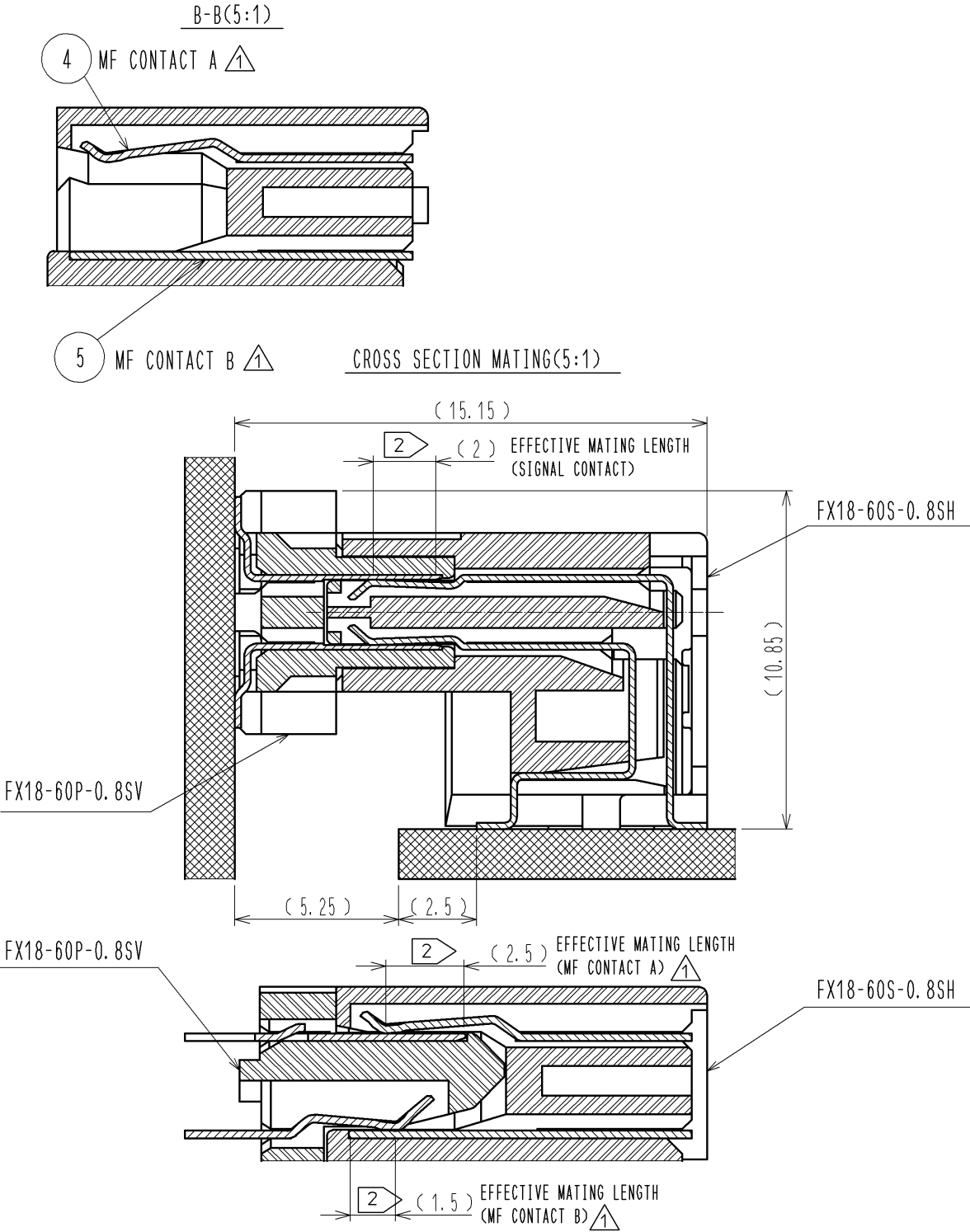
APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C ⁽¹⁾		STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C ⁽²⁾
	VOLTAGE	100 V AC		STORAGE HUMIDITY RANGE	40 % TO 70 % ⁽²⁾
	CURRENT	0.5 A (SIGNAL CONTACT) ⁽³⁾ 3 A (MF CONTACT)		OPERATING HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	QT AT
CONSTRUCTION					
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	x x
MARKING		CONFIRMED VISUALLY.			x x
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE		100 mA(DC OR 1000Hz)		SIGNAL CONTACT : 90 mΩ MAX. MF CONTACT : 30 mΩ MAX.	x —
INSULATION RESISTANCE		250 V DC.		1000 MΩ MIN.	x —
VOLTAGE PROOF		300 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	x —
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES		MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 40 N MAX. WITHDRAWAL FORCE: 4 N MIN.	x —
MECHANICAL OPERATION		500 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
VIBRATION		FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
SHOCK		490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			x —
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)		EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX.	x —
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER: WITHIN 2~3 MIN)		② INSULATION RESISTANCE : 1000 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
SULFUR DIOXIDE		EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		NO HEAVY CORROSION.	x —
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	x —
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.	x —
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
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REMARKS ⁽¹⁾ INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING. ⁽²⁾ "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB. ⁽³⁾ THE RATED CURRENT APPLIES TO PER CONTACT. Unless otherwise specified, refer to JIS-C-5402.			APPROVED	HS. OKAWA	09. 10. 13
			CHECKED	K.I. HIROKAWA	09. 10. 13
			DESIGNED	TH. SANO	09. 10. 13
			DRAWN	TH. SANO	09. 10. 13
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC4-159075-00
HRS	SPECIFICATION SHEET		PART NO.	FX18-60P-0. 8SH	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL579-0003-8-00	△ 1/1

APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C ⁽¹⁾		STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C ⁽²⁾
	VOLTAGE	100 V AC		STORAGE HUMIDITY RANGE	40 % TO 70 % ⁽²⁾
	CURRENT	0.5 A (SIGNAL CONTACT) ⁽³⁾ 3 A (MF CONTACT)		OPERATING HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	QT AT
CONSTRUCTION					
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	x x
MARKING		CONFIRMED VISUALLY.			x x
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE		100 mA(DC OR 1000Hz)		SIGNAL CONTACT : 90 mΩ MAX. MF CONTACT : 30 mΩ MAX.	x —
INSULATION RESISTANCE		250 V DC.		1000 MΩ MIN.	x —
VOLTAGE PROOF		300 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	x —
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES		MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 30 N MAX. WITHDRAWAL FORCE: 3 N MIN.	x —
MECHANICAL OPERATION		500 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
VIBRATION		FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
SHOCK		490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			x —
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)		EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX.	x —
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER: WITHIN 2~3 MIN)		② INSULATION RESISTANCE : 1000 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
SULFUR DIOXIDE		EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		NO HEAVY CORROSION.	x —
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	x —
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	x —
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
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			CHECKED	K.I. HIROKAWA	09. 10. 13
			DESIGNED	TH. SANO	09. 10. 13
			DRAWN	TH. SANO	09. 10. 13
Unless otherwise specified, refer to JIS-C-5402.					
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC4-159081-00
HRS	SPECIFICATION SHEET		PART NO.	FX18-40S-0. 8SH	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL579-0009-4-00	△ 1/1

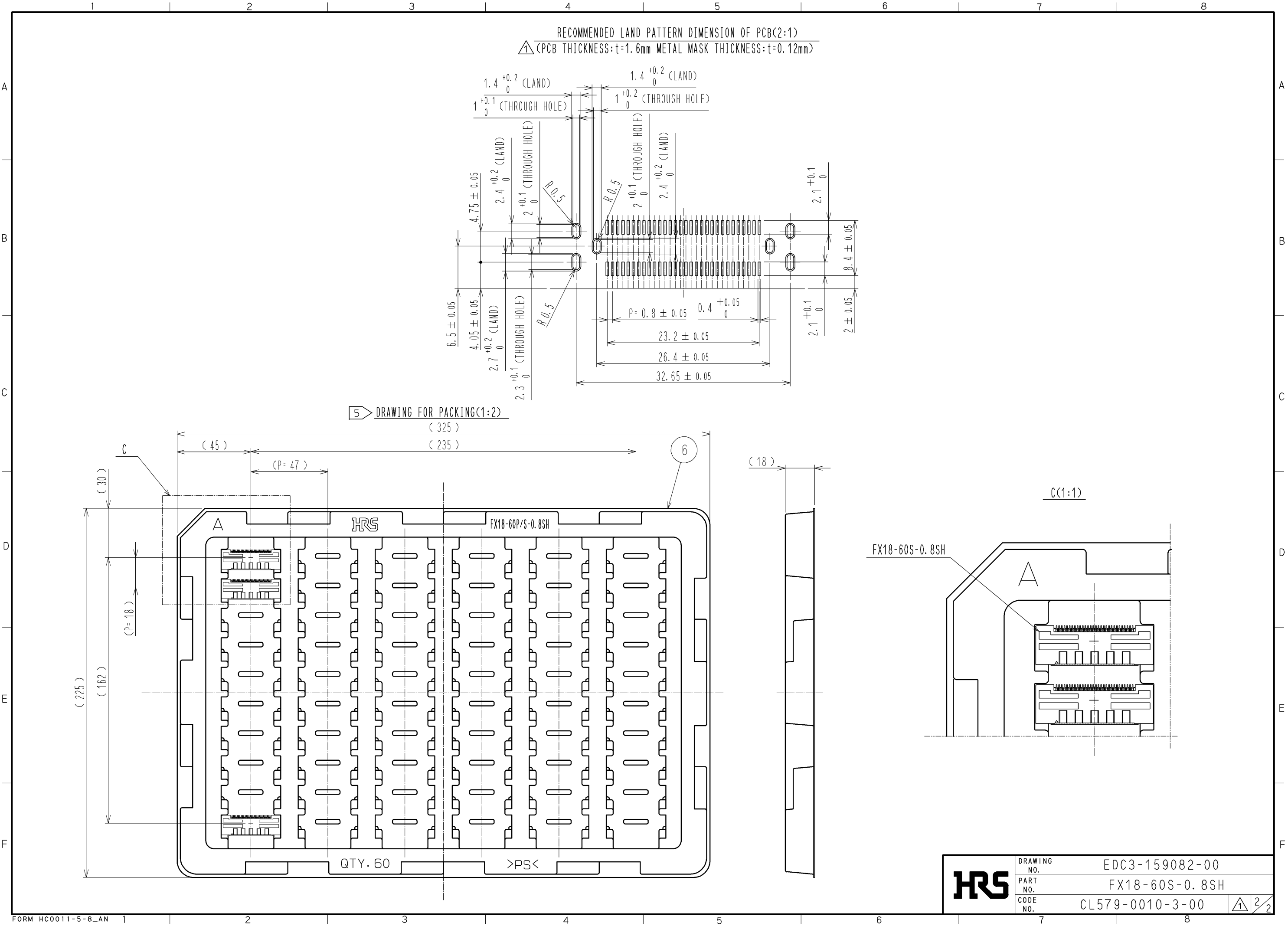
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	VOLTAGE	100 V AC		STORAGE HUMIDITY RANGE	40 % TO 70 % ⁽²⁾
	CURRENT	0.5 A (SIGNAL CONTACT) ⁽³⁾ 3 A (MF CONTACT)		OPERATING HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	QT AT
CONSTRUCTION					
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	x x
MARKING		CONFIRMED VISUALLY.			x x
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE		100 mA(DC OR 1000Hz)		SIGNAL CONTACT : 90 mΩ MAX. MF CONTACT : 30 mΩ MAX.	x —
INSULATION RESISTANCE		250 V DC.		1000 MΩ MIN.	x —
VOLTAGE PROOF		300 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	x —
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES		MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 30 N MAX. WITHDRAWAL FORCE: 3 N MIN.	x —
MECHANICAL OPERATION		500 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
VIBRATION		FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
SHOCK		490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			x —
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)		EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX.	x —
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER: WITHIN 2~3 MIN)		② INSULATION RESISTANCE : 1000 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
SULFUR DIOXIDE		EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		NO HEAVY CORROSION.	x —
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	x —
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.	x —
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REMARKS ⁽¹⁾ INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING. ⁽²⁾ "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB. ⁽³⁾ THE RATED CURRENT APPLIES TO PER CONTACT. Unless otherwise specified, refer to JIS-C-5402.			APPROVED	HS. OKAWA	09. 10. 13
			CHECKED	K.I. HIROKAWA	09. 10. 13
			DESIGNED	TH. SANO	09. 10. 13
			DRAWN	TH. SANO	09. 10. 13
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC4-159560-00
HRS	SPECIFICATION SHEET		PART NO.	FX18-40P-0. 8SV	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL579-0016-0-00	△ 1/1

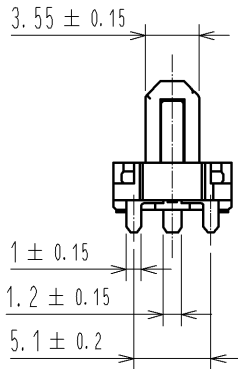
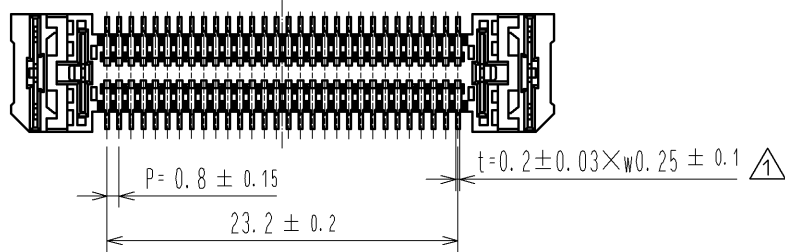
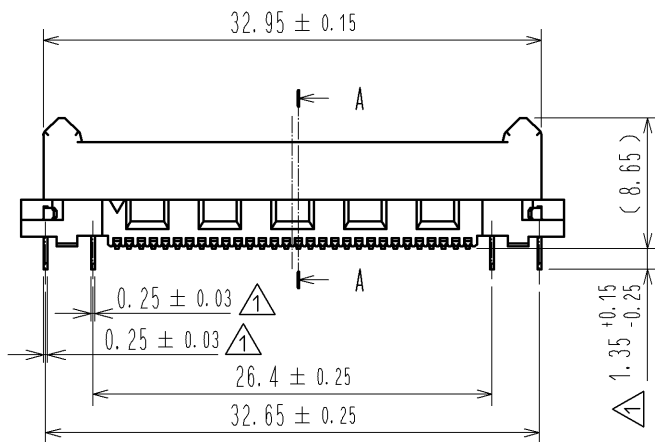
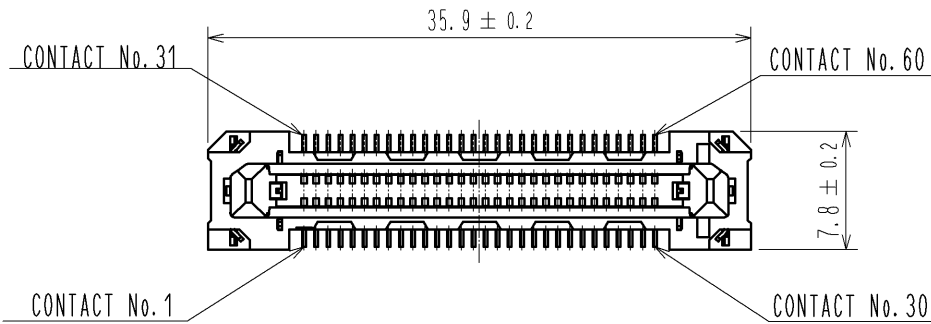


NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
① ② CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)
WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
① ③ MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
④ IT SHOWS CONNECTOR'S CENTRE OF GRAVITY AND VACUUM PICKUP AREA.
⑤ THIS IS PACKAGED IN TRAY. (60psc/TRAY)
6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

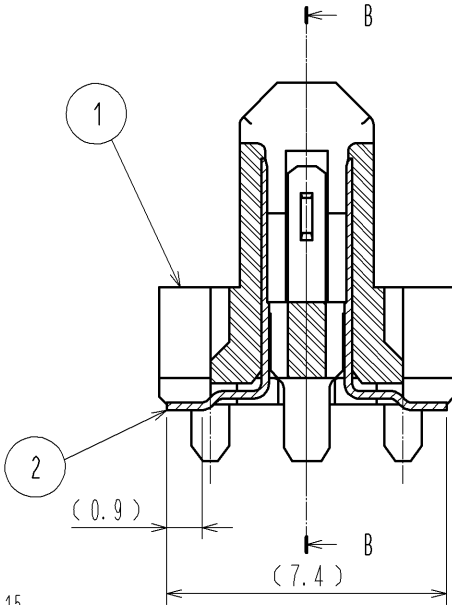


3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1μm	6	POLYSTYRENE	
		LEAD AREA:GOLD 0.03μm	5	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1μm
		UNDER PLATING:NICKEL 1.3μm ①			LEAD AREA:TIN-PLATING 1μm
2	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1μm	4	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1μm
		LEAD AREA:GOLD 0.03μm			LEAD AREA:TIN-PLATING 1μm
		UNDER PLATING:NICKEL 1.3μm ①			UNDER PLATING:NICKEL 1.3μm ①
1	POLYAMIDE	BLACK UL94V-0			
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm	① ②	SCALE 2 : 1	COUNT 15	DESCRIPTION OF REVISIONS DIS-F-004158	DESIGNED KI. HIROKAWA
HRS HIROSE ELECTRIC CO., LTD.		APPROVED : HS. OKAWA	09. 04. 24	DRAWING NO.	EDC3-159082-00
		CHECED : HS. OZAWA	09. 04. 24	PART NO.	FX18-60S-0.8SH
		DESIGNED : KI. HIROKAWA	09. 04. 24	CODE NO.	CL579-0010-3-00
		DRAWN : KI. HIROKAWA	09. 04. 24		① ②

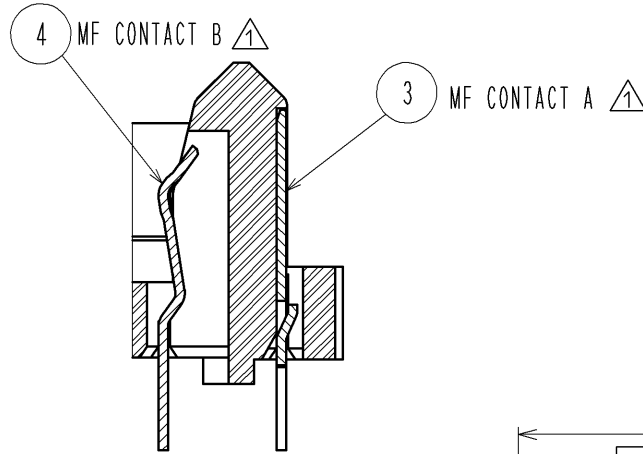




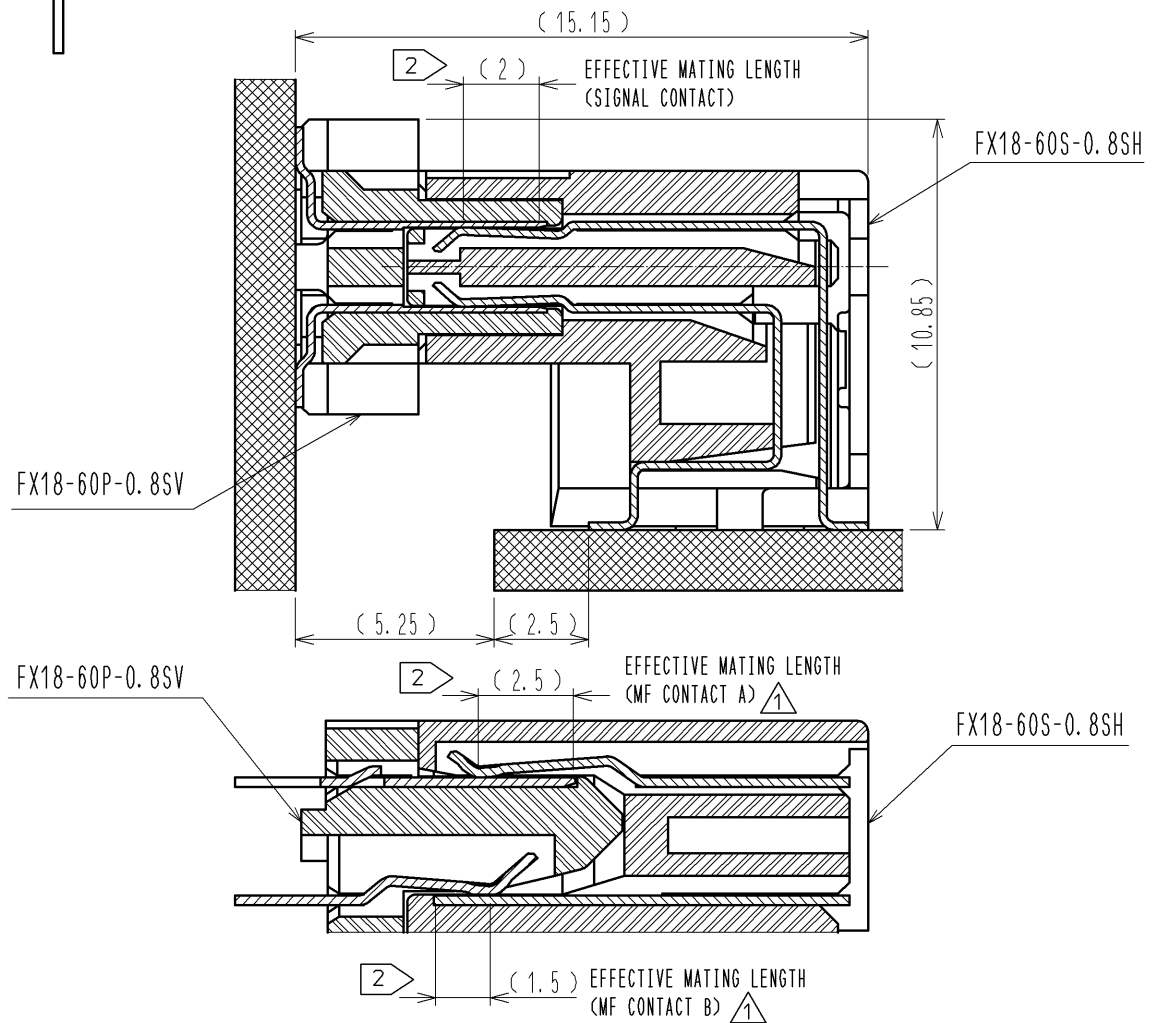
A-A(5:1)



B-B(5:1)

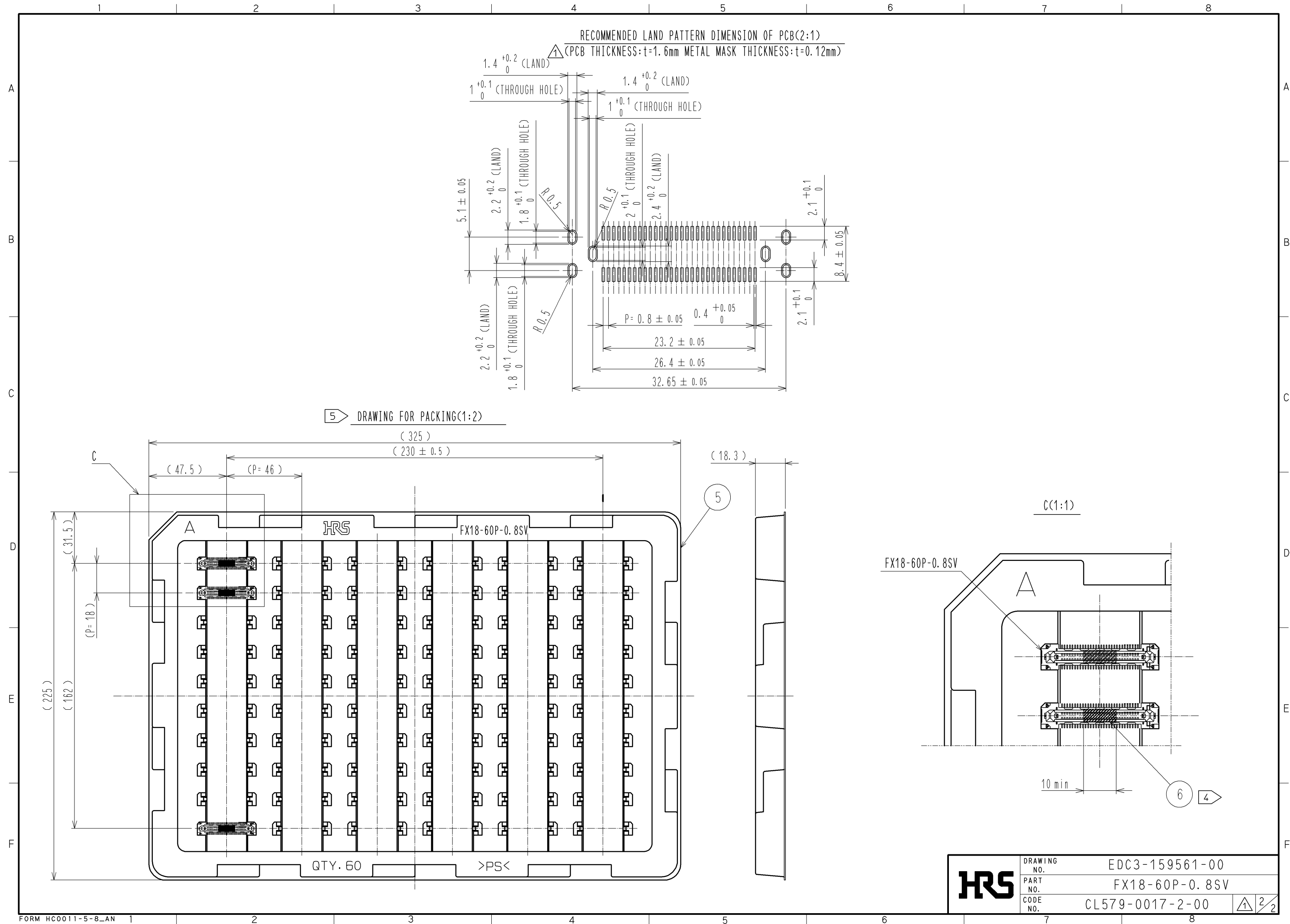


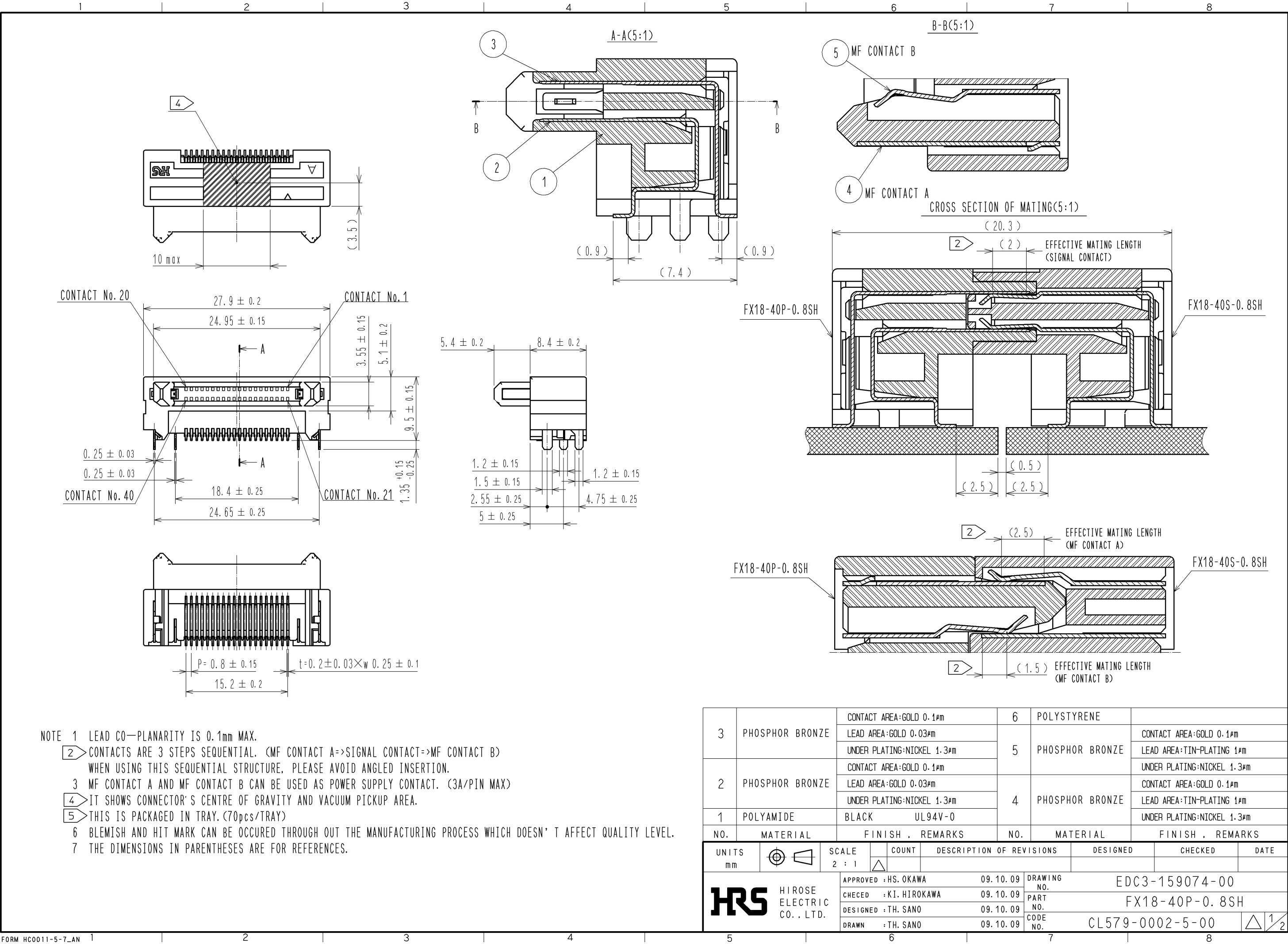
CROSS SECTION OF MATING(5:1)

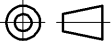


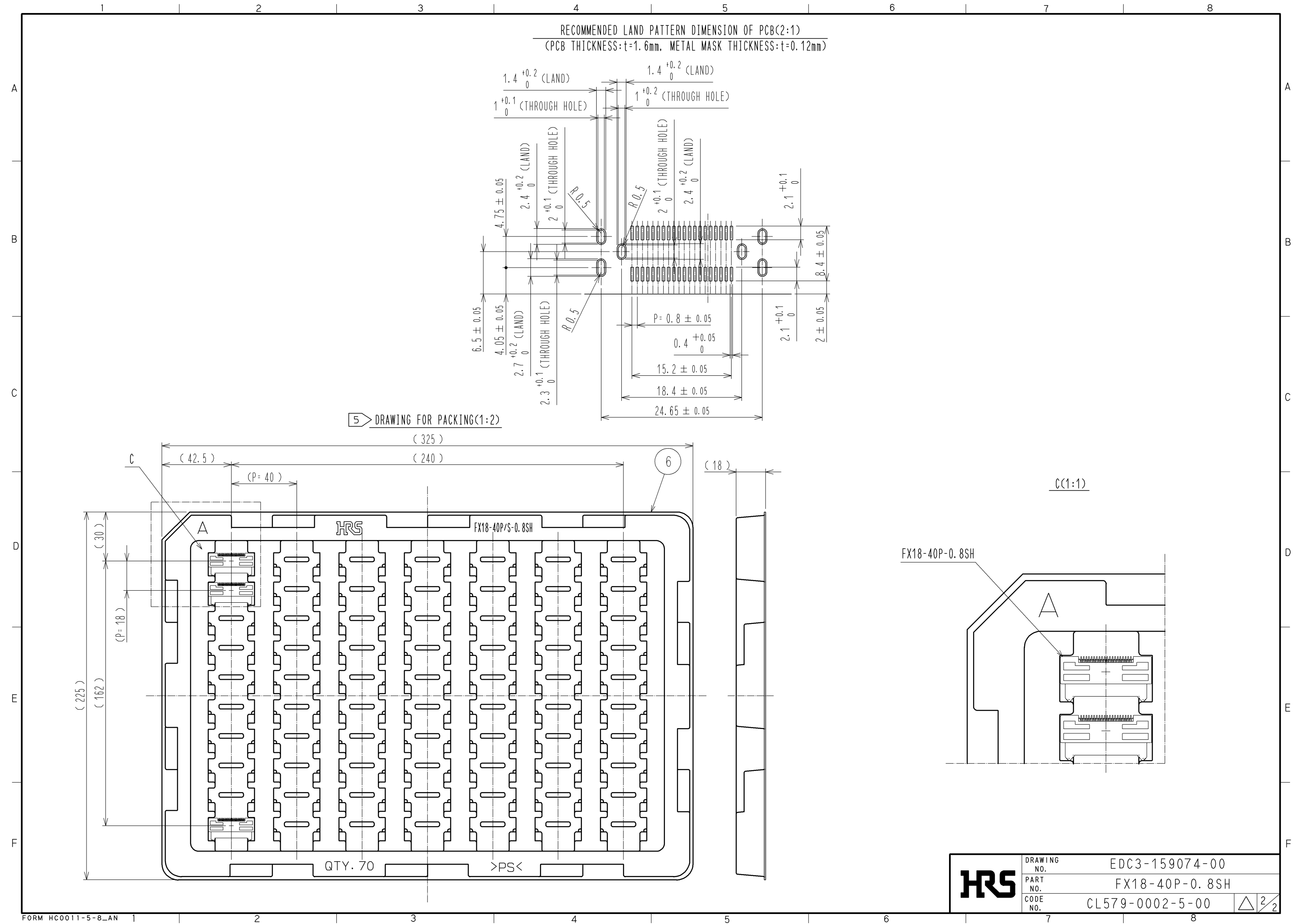
- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
- △2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)
WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
- △3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
- 4 IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)
REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
- 5 THIS IS PACKAGED IN TRAY. (60pcs/TRAY)
- 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
- 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

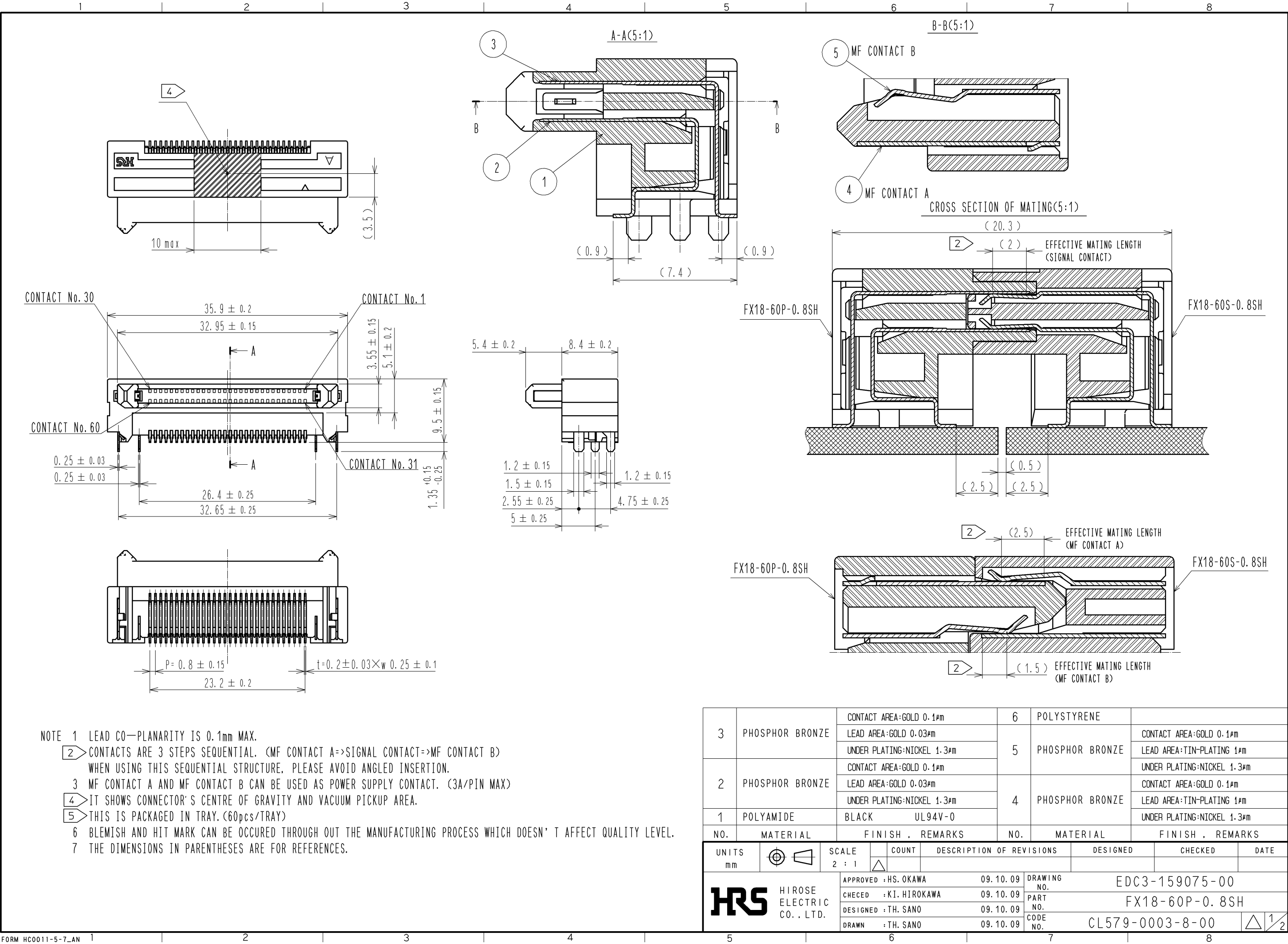
3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm	6	POLYIMIDE	
		LEAD AREA:TIN-PLATING 1 μm			
		UNDER PLATING:NICKEL 1.3 μm △1			
2	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm	5	POLYSTYRENE	
		LEAD AREA:GOLD 0.03 μm			
		UNDER PLATING:NICKEL 1.3 μm △1			
1	POLYAMIDE	BLACK UL94V-0	4	PHOSPHOR BRONZE △1	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm		SCALE 2 : 1	COUNT 14	DESCRIPTION OF REVISIONS DIS-F-004158	DESIGNED KI. HIROKAWA
HIROSE ELECTRIC CO., LTD.		APPROVED : HS. OKAWA	09.04.24	DRAWING NO.	EDC3-159561-00
		CHECED : HS. OZAWA	09.04.24	PART NO.	FX18-60P-0.8SV
		DESIGNED : KI. HIROKAWA	09.04.24	CODE NO.	CL579-0017-2-00
		DRAWN : KI. HIROKAWA	09.04.24		
					1/2

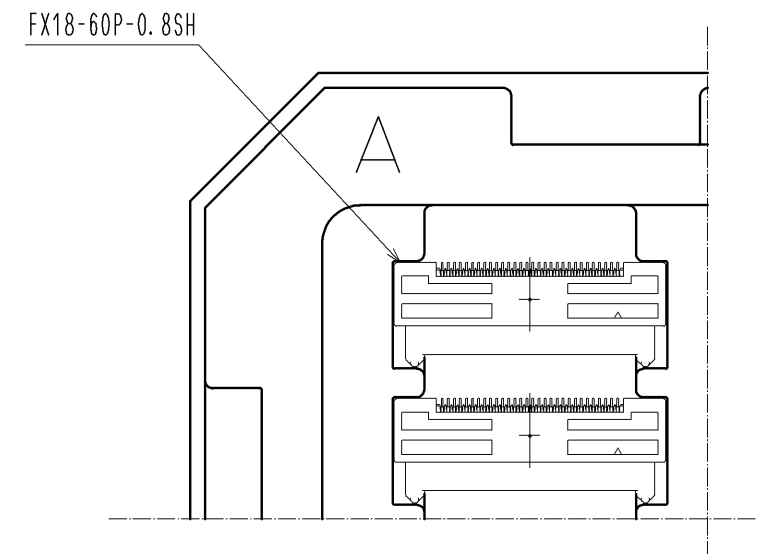
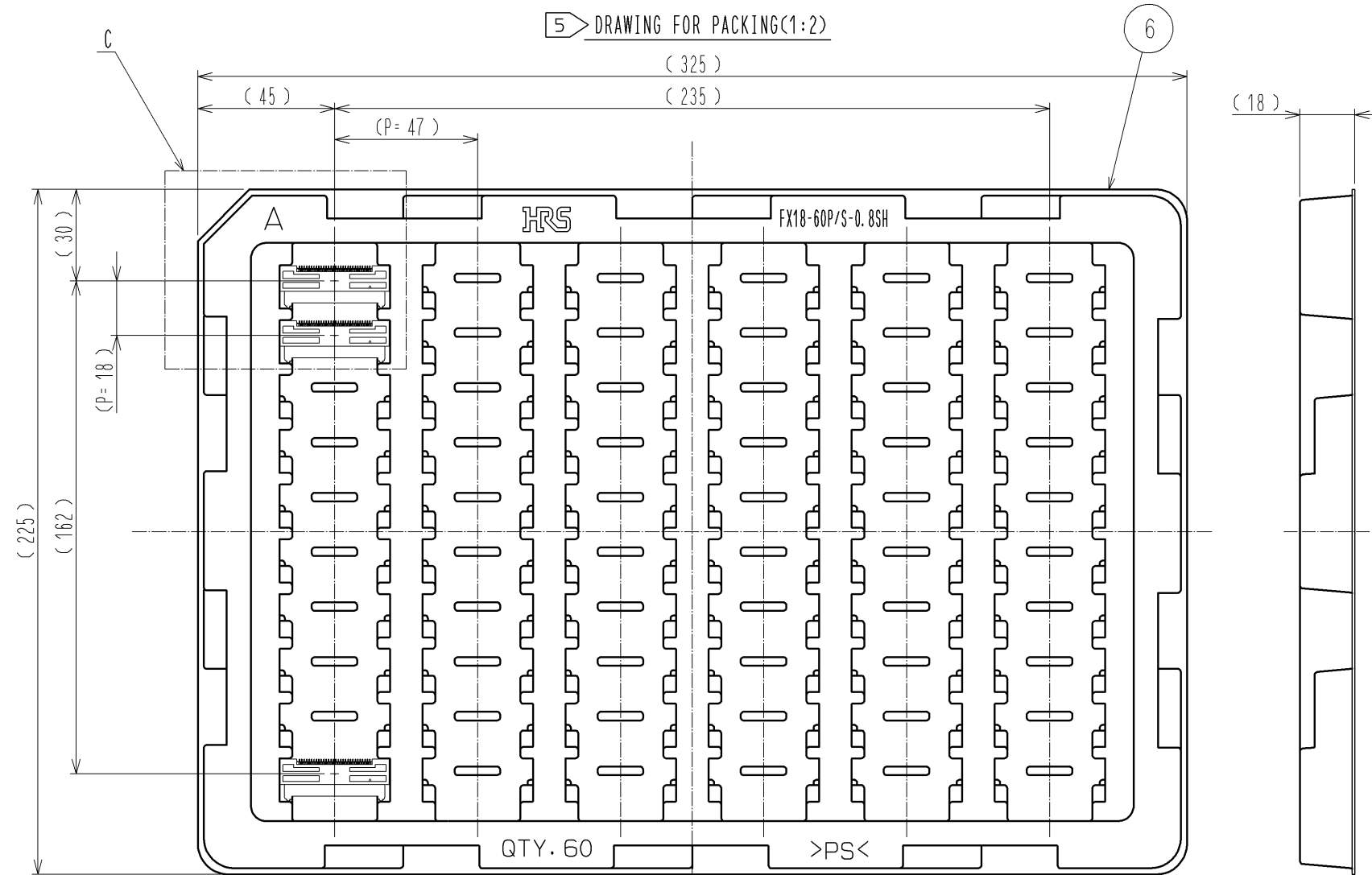
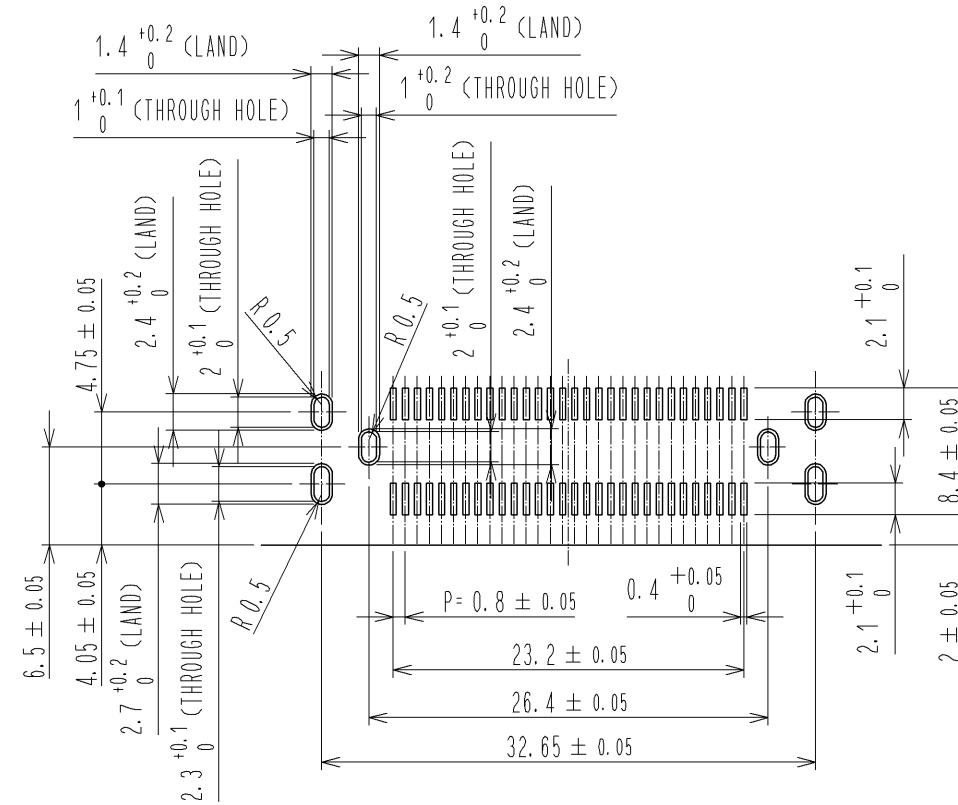


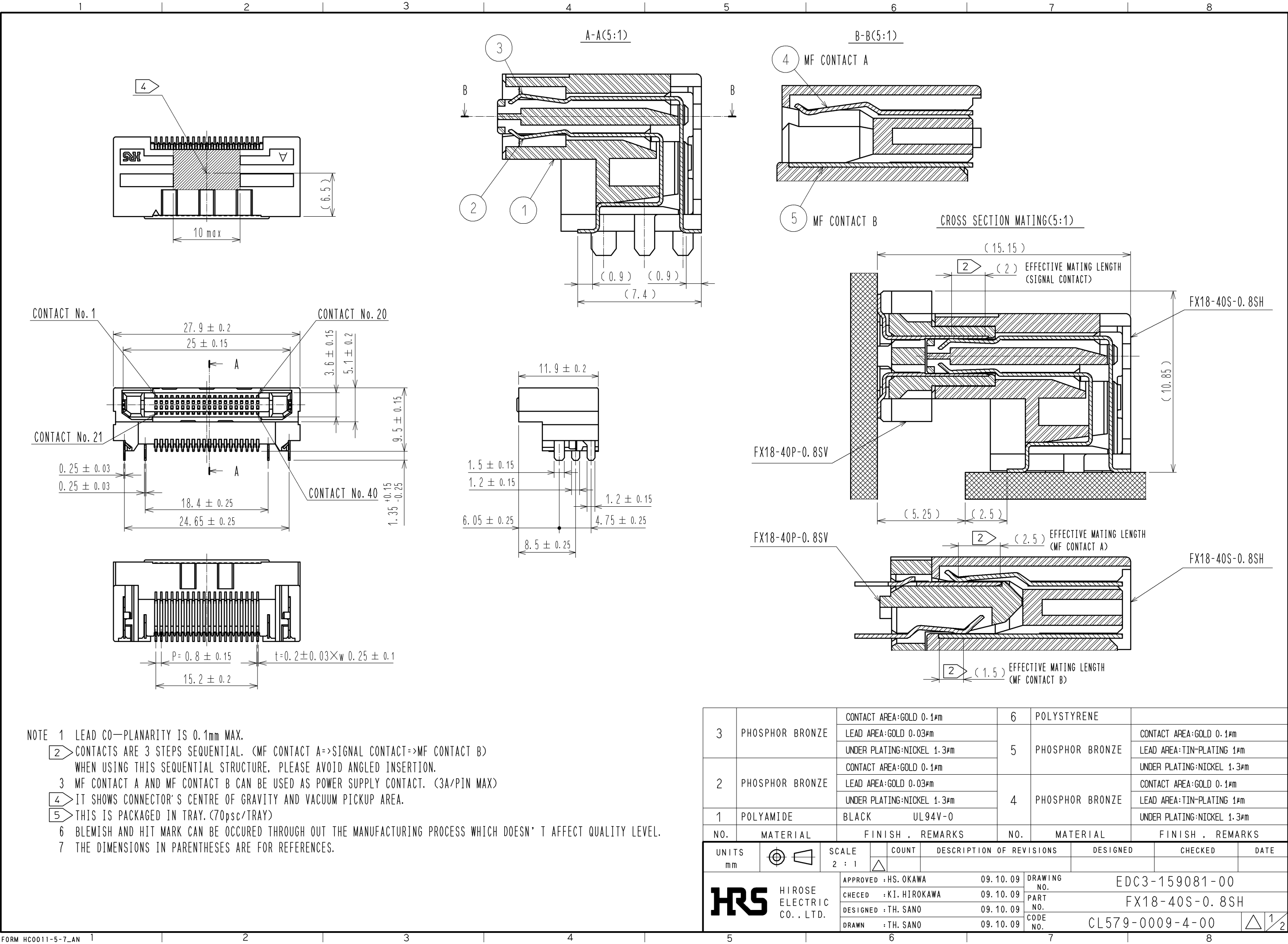


3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1μm		6	POLYSTYRENE								
		LEAD AREA:GOLD 0.03μm		5	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1μm							
		UNDER PLATING:NICKEL 1.3μm				LEAD AREA:TIN-PLATING 1μm							
2	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1μm		4	PHOSPHOR BRONZE	UNDER PLATING:NICKEL 1.3μm							
		LEAD AREA:GOLD 0.03μm				CONTACT AREA:GOLD 0.1μm							
		UNDER PLATING:NICKEL 1.3μm				LEAD AREA:TIN-PLATING 1μm							
1	POLYAMIDE	BLACK UL94V-0				UNDER PLATING:NICKEL 1.3μm							
NO.		MATERIAL		FINISH . REMARKS		NO.		MATERIAL		FINISH . REMARKS			
UNITS mm				SCALE 2 : 1		COUNT	DESCRIPTION OF REVISIONS			DESIGNED		CHECKED	DATE
 HIROSE ELECTRIC CO. , LTD.				APPROVED : HS. OKAWA		09.10.09	DRAWING NO.		EDC3-159074-00				
				CHECED : KI. HIROKAWA		09.10.09	PART NO.		FX18-40P-0.8SH				
				DESIGNED : TH. SANO		09.10.09	CODE NO.		CL579-0002-5-00				
				DRAWN : TH. SANO		09.10.09							
									1/2				



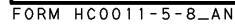


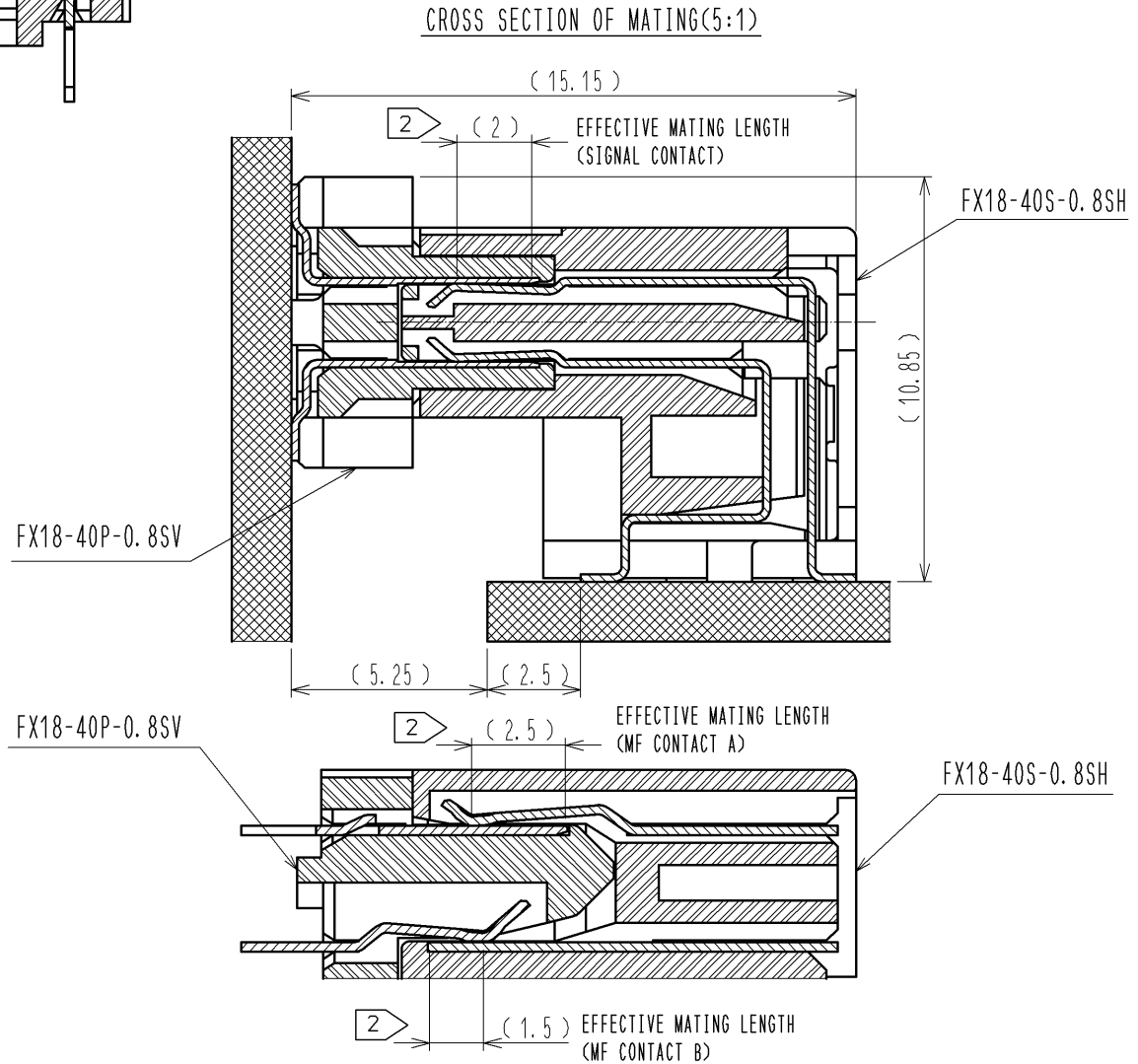
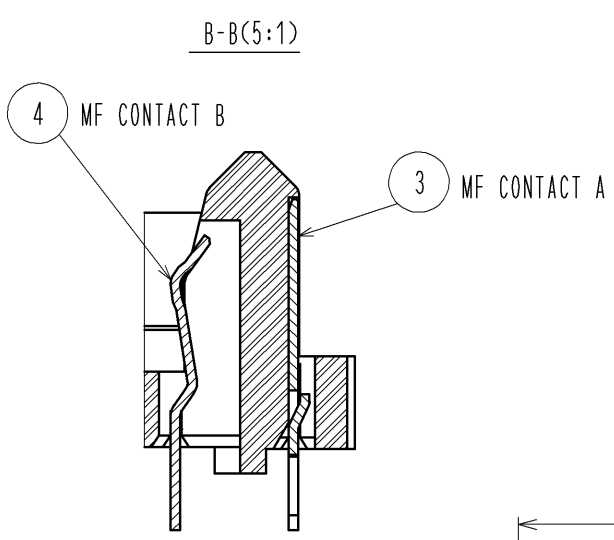
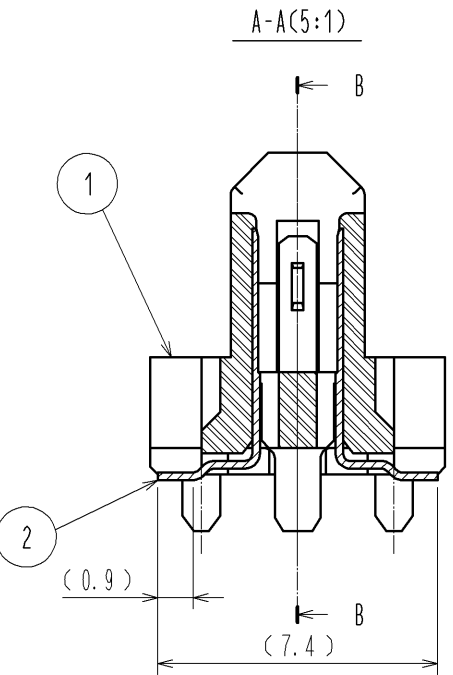
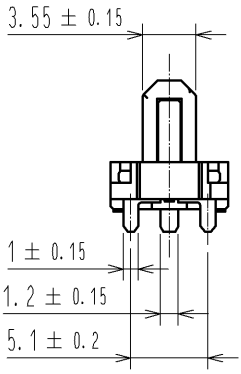
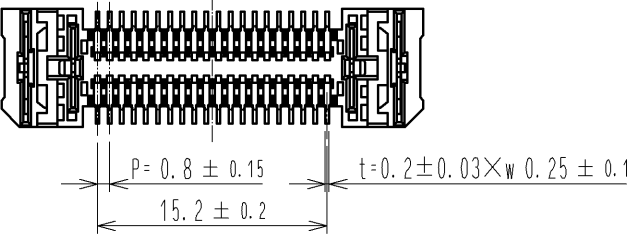
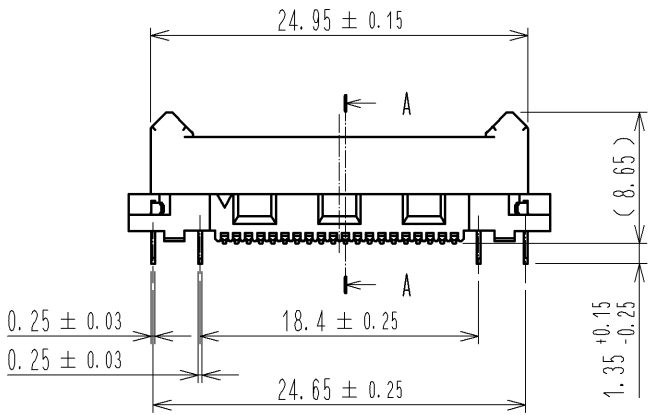
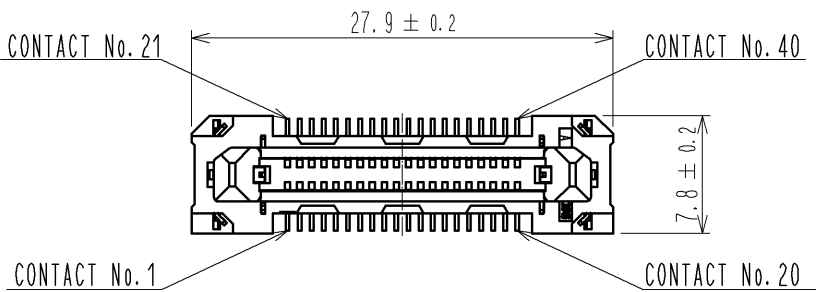




NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)
WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
4 IT SHOWS CONNECTOR'S CENTRE OF GRAVITY AND VACUUM PICKUP AREA.
5 THIS IS PACKAGED IN TRAY. (70psc/TRAY)
6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm	6	POLYSTYRENE	
		LEAD AREA:GOLD 0.03µm	5	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm
		UNDER PLATING:NICKEL 1.3µm			LEAD AREA:TIN-PLATING 1µm
2	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm	4	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm
		LEAD AREA:GOLD 0.03µm			LEAD AREA:TIN-PLATING 1µm
		UNDER PLATING:NICKEL 1.3µm			UNDER PLATING:NICKEL 1.3µm
1	POLYAMIDE	BLACK UL94V-0			
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm		SCALE 2 : 1	COUNT		DESCRIPTION OF REVISIONS
HRS		APPROVED : HS. OKAWA	09.10.09		DESIGNED
HIROSE ELECTRIC CO., LTD.		CHECED : KI. HIROKAWA	09.10.09		CHECKED
		DESIGNED : TH. SANO	09.10.09		DATE
		DRAWN : TH. SANO	09.10.09		
		DRAWING NO. EDC3-159081-00		PART NO. FX18-40S-0.8SH	
		CODE NO. CL579-0009-4-00		1/2	





- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
- 2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)
WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
- 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
- 4 IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)
REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
- 5 THIS IS PACKAGED IN TRAY. (70pcs/TRAY)
- 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
- 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm	6	POLYIMIDE	
		LEAD AREA:TIN-PLATING 1 μm			
		UNDER PLATING:NICKEL 1.3 μm			
2	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm	5	POLYSTYRENE	
		LEAD AREA:GOLD 0.03 μm			
		UNDER PLATING:NICKEL 1.3 μm			
1	POLYAMIDE	BLACK UL94V-0	4	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm
					LEAD AREA:TIN-PLATING 1 μm
					UNDER PLATING:NICKEL 1.3 μm
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm		SCALE 2 : 1	COUNT △	DESCRIPTION OF REVISIONS	
				DESIGNED	CHECKED
					DATE
HRS HIROSE ELECTRIC CO., LTD.		APPROVED : HS. OKAWA	09.10.09	DRAWING NO.	EDC3-159560-00
		CHECED : KI. HIROKAWA	09.10.09	PART NO.	FX18-40P-0.8SV
		DESIGNED : TH. SANO	09.10.09	CODE NO.	CL579-0016-0-00
		DRAWN : TH. SANO	09.10.09		

